

News Release

April 1, 2024
LINK-US Co., Ltd.

LINK-US Co., Ltd. raised JPY 200 million by Resona Bank

LINK-US Co., Ltd. (Crescendo Building, 2-3-4 Shinyokohama, Kohokuku, Yokohama City; CEO: Jun Mitsuyuki) which develops and sells the world's only metal bonding equipment that uses ultrasonic complex vibrations, today announced that it has entered into an overdraft agreement with Resona Bank, Ltd. for 200 million yen. LINK-US Co., Ltd. develops and sells the world's only metal bonding equipment that uses ultrasonic complex vibrations, which enables highly efficient and low-damage bonding compared to traditional methods. As society moves towards electrification and automation to achieve carbon neutrality, the demand for innovative technology and products is increasing globally. This agreement will help us expand our business by securing working capital that can be raised dynamically and efficiently.

[About LINK-US]

We develop, manufacture, and sell bonding equipment that use ultrasonic complex vibrations to bond metals. Ultrasonic complex vibration bonding enables high-efficiency and low-damage bonding compared to conventional bonding methods, and is performed using ultrasonic vibrations with circular or elliptical trajectories. It is a patented technology that is the only one of its kind in the world. We will make a significant contribution to the electrification and automation of next-generation batteries, including solid-state batteries for EVs, and power devices.

Company name: LINK-US Co., Ltd.

Head office: Crescendo Building, 2-3-4 Shinyokohama, Kohokuku, Yokohama City

CEO: Jun Mitsuyuki

Founded: August 18, 2014

Business activities: Development and sales of metal bonding equipment and other equipment that apply ultrasonic complex vibrations and powerful ultrasonic technology

URL : <https://link-us.co.jp/en>

[For Inquiries Regarding This Press Release]

info@link-us.jp (LINK-US Co., Ltd. Administrative Department)